

ATTACHMENT PHOTOGRAPHS OF Interior photos

Photo 1

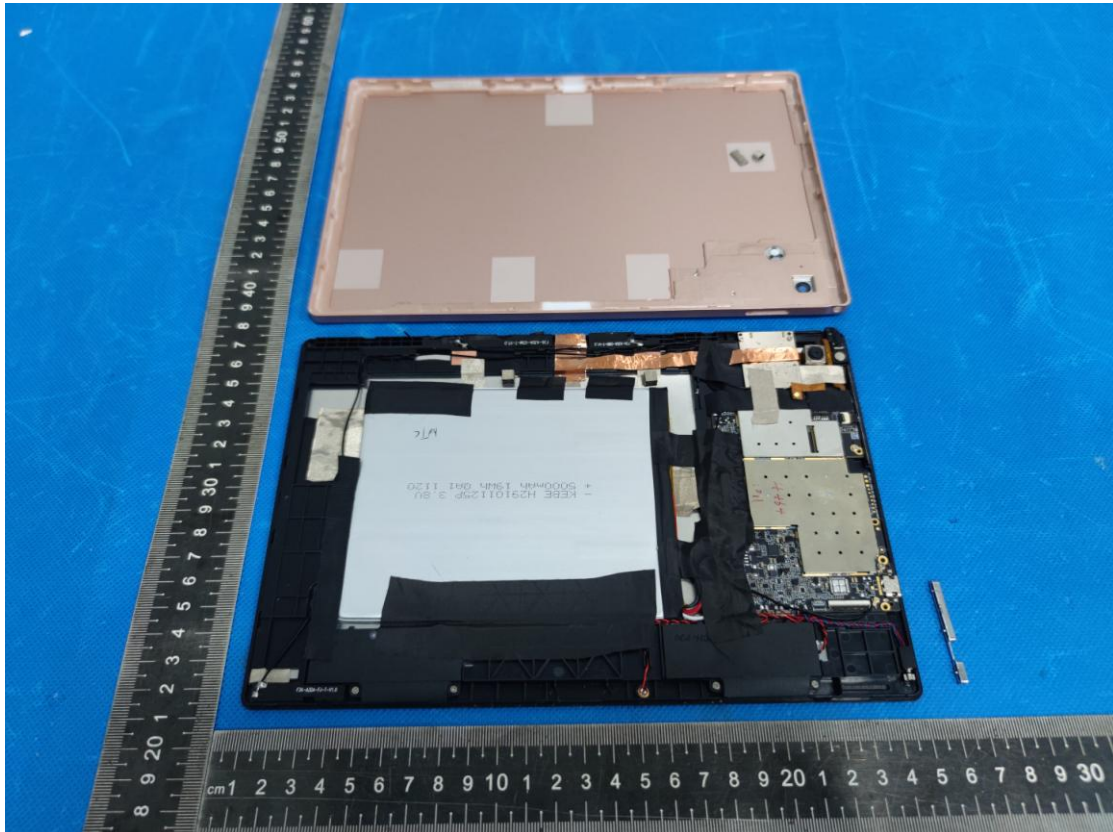


Photo 2

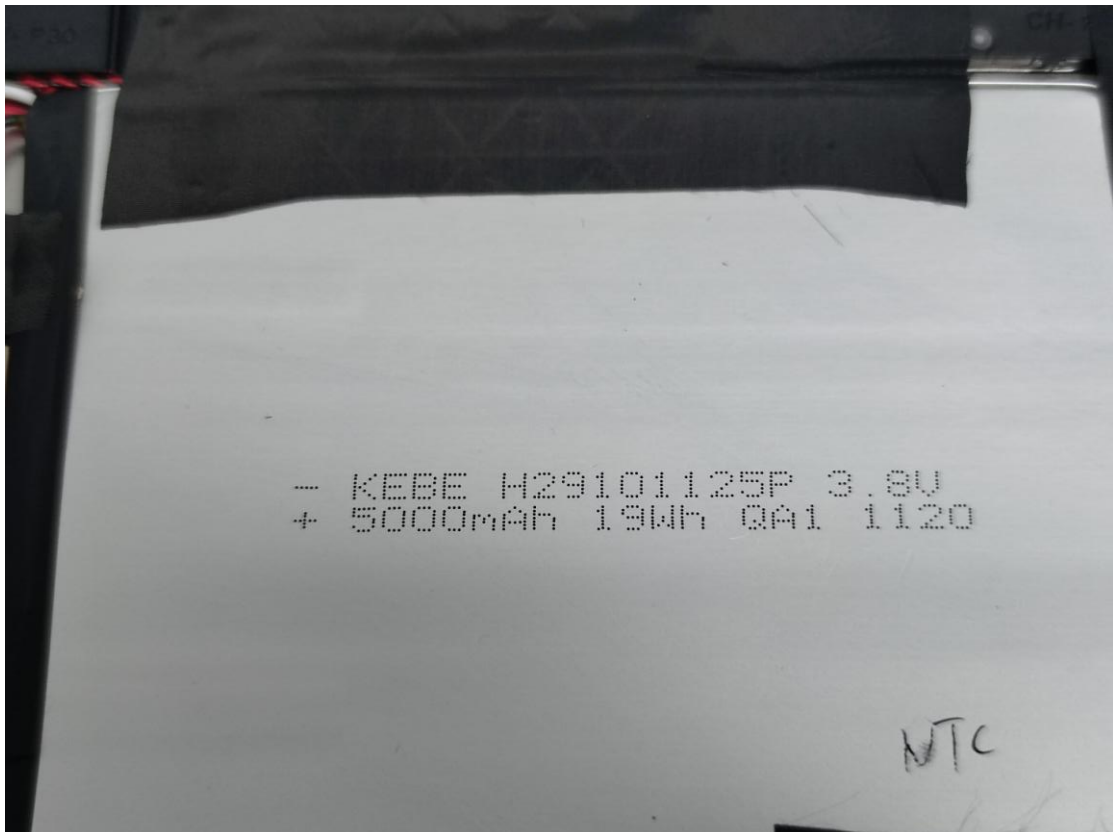


Photo 3

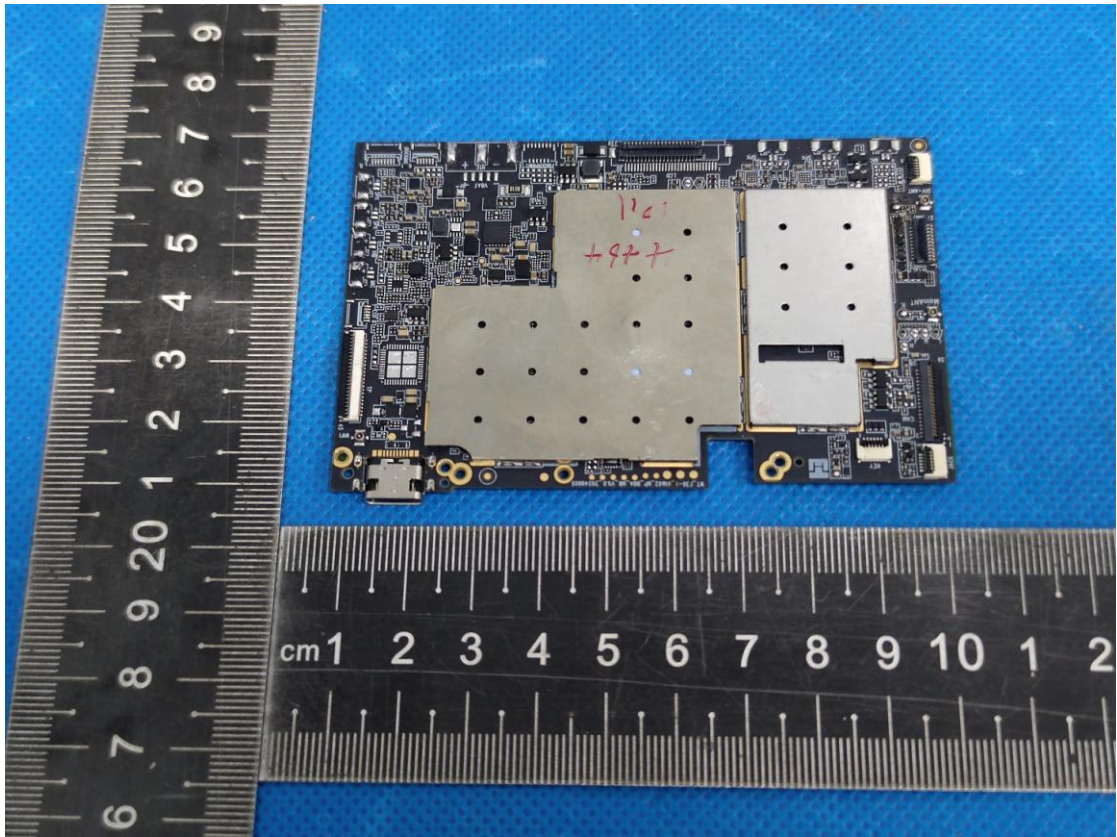


Photo 4

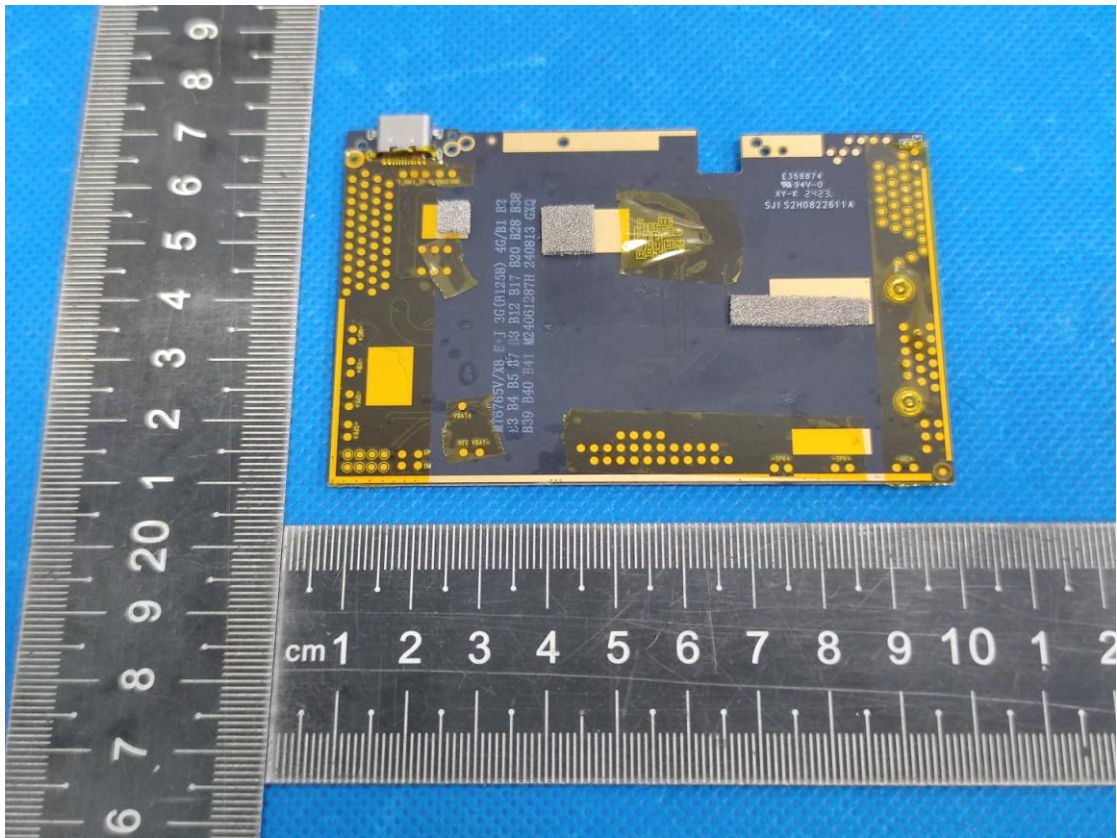


Photo 5

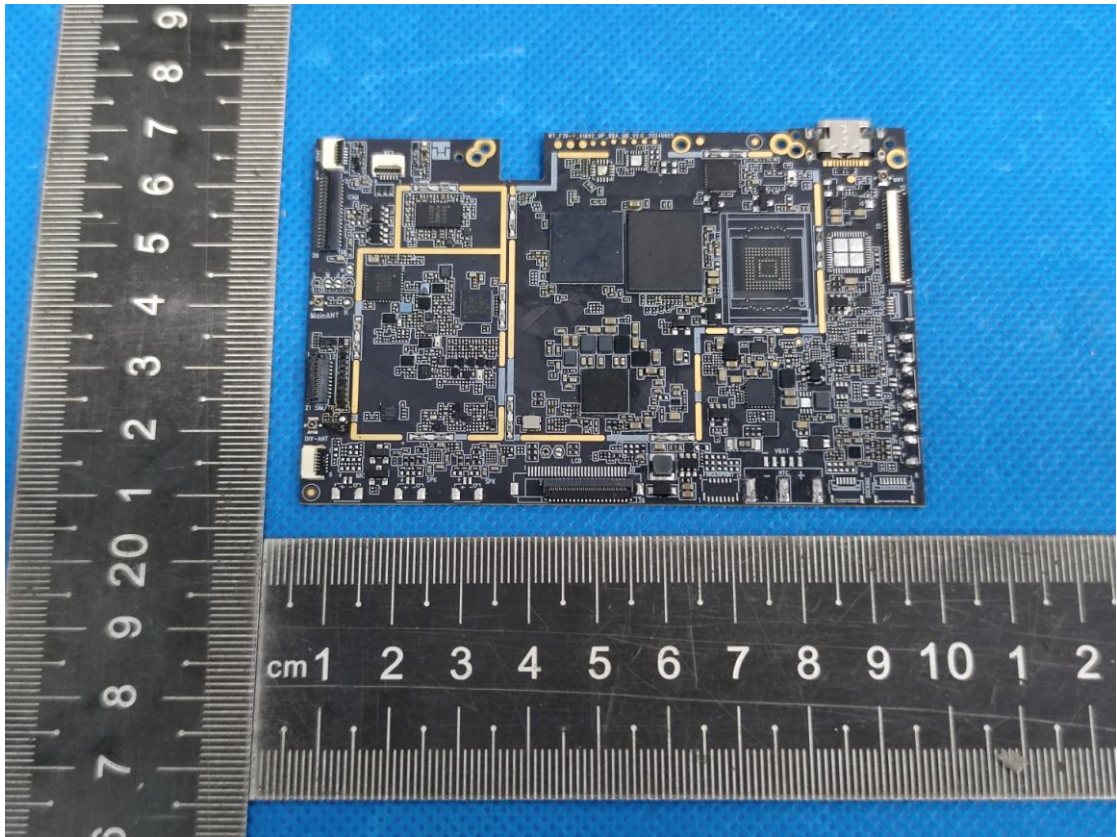
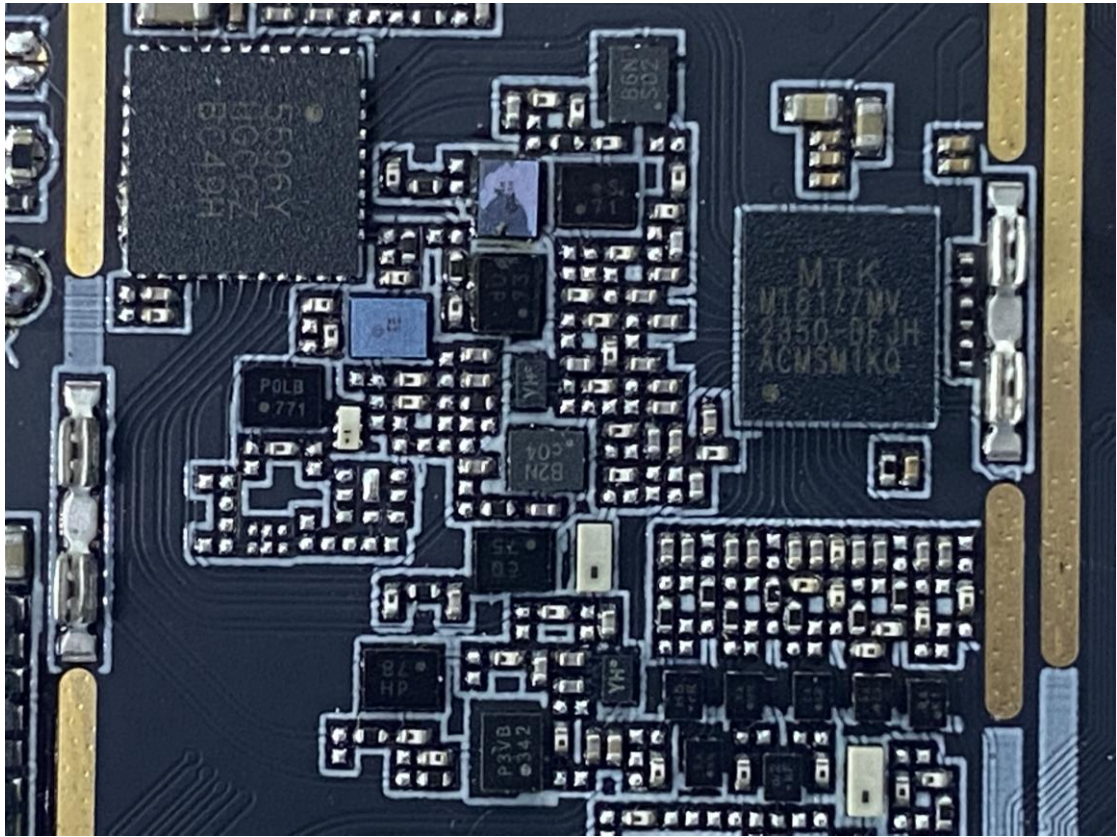


Photo 6



A detailed microscopic view of a mobile phone's internal circuit board. The central focus is a large, square, black integrated circuit (IC) chip. On its surface, the text '5627Y', 'KEMRE', and 'BD111' is printed in a light color. The chip is surrounded by a dense array of smaller components, including numerous surface-mount capacitors and resistors. A prominent gold-colored metal frame or shield is visible, partially enclosing the central chip area. To the right, a long, narrow component, possibly a memory module or a connector, is visible. The overall layout is complex, with various traces and components soldered onto the dark-colored PCB.

Photo 9

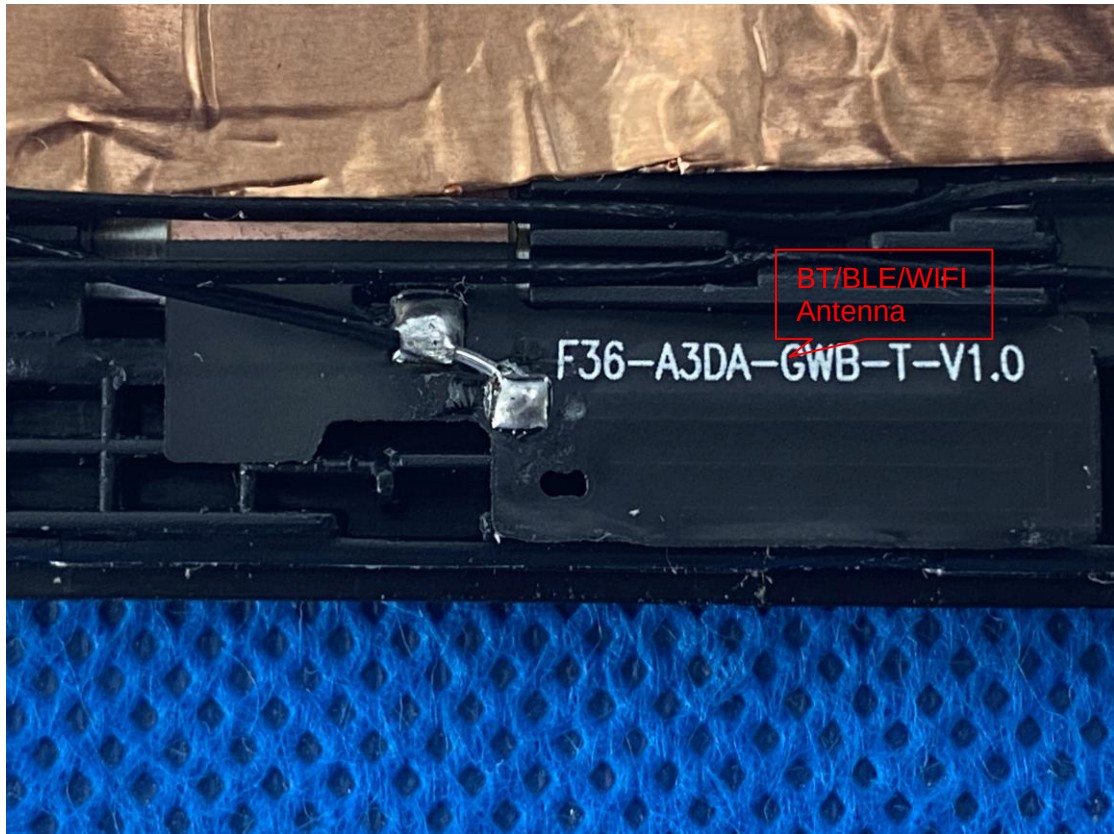


Photo 10

